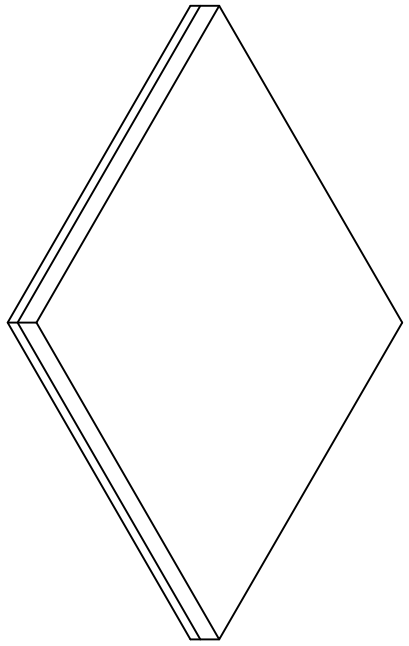


| REVISION HISTORY | | | | |
|------------------|---------------------------------|----------|----------|----------|
| NO | DESCRIPTION | DATE | DESIGNED | RELEASED |
| 00 | INITIAL RELEASE PER DON COTYSEZ | 01/10/00 | SBEFO | GSCHU |



7. REFERENCE SPECIFICATIONS:
 A. AAWW SPEC #001-0531-2234; PACKING OPERATION PROCEDURE.
 B. AAWW SPEC #001-0519-2082; MARKING.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 128.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 12 X 12.
2. THE BASIC SOLDER BALL GRID PITCH IS 0.80.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

| UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS | | FRONT VIEW PROJECTION | | TITLE | | DATE | | APPROVALS | | DATE | |
|--|----------------|-----------------------|--|-------|------|------|------|-----------|------|------|------|
| DECIMAL | XX ± 0.1 | ± 1° | | DATE | DATE | DATE | DATE | DATE | DATE | DATE | DATE |
| INTEGRITY DIM AND TOL PER | X.XXX ± 0.030 | ± 1° | | DATE | DATE | DATE | DATE | DATE | DATE | DATE | DATE |
| INTERPRETATION | SEE CLAS - 183 | ± 1° | | DATE | DATE | DATE | DATE | DATE | DATE | DATE | DATE |
| UNIT | N/A | ± 1° | | DATE | DATE | DATE | DATE | DATE | DATE | DATE | DATE |
| FINISH | N/A | ± 1° | | DATE | DATE | DATE | DATE | DATE | DATE | DATE | DATE |
| DO NOT SCALE DRAWING | N/A | ± 1° | | DATE | DATE | DATE | DATE | DATE | DATE | DATE | DATE |



PACKAGE OUTLINE - CTEGA 128,
 11.00mm X 11.00mm, 2 LAYER, AAWW
 0.80mm PITCH, LAMINATE SUBSTRATE.

| DATE | BY | CHKD | DATE | BY | CHKD |
|----------|------------|------|----------|-----------|------|
| 01/10/00 | G. SCHULTZ | | 01/10/00 | T. PANCIK | |
| | | | | | |